

Amendment to the Specification:

The Applicants respectfully request that paragraphs [0027] and [0032] of the specification be replaced with the following edited paragraphs:

[0027] In accordance with one embodiment of the invention a chelating agent is tailored to bind with atoms of a specific metal or metal alloy in order to selectively etch particular metals or allows alloys while leaving intact other metal films as well as the non-metal films.

[0032] In accordance with another embodiment a chelating agent is made to target specific metals or alloys by varying the media in which the chelating agent is employed. In accordance with alternative embodiments the chelating agents may be employed [[I-n]] in an acid solution, a base solution, a solvent solution, or a de-ionized water (DIW) solution.